

L Number	Hits	Search Text	DB	Time stamp
-	56	semiconductor adj substrate and inductor and capacitor and radio adj frequency and etching and monitoring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 17:36
-	130	(438/8).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:26
-	114	(438/13).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:28
-	259	radio adj frequency adj detection or radio adj frequency adj detector	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:30
-	17251	chemical adj etching	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 17:48
-	1	(radio adj frequency adj detection or radio adj frequency adj detector) and (chemical adj etching)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:33
-	141	lateral adj undercut	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:36
-	15708	resonate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:36
-	110	(chemical adj etching) and resonate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:36
-	1133640	semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:36
-	41	((chemical adj etching) and resonate) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:40
-	130	quartz adj crystal adj monitor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:45
-	165128	receiver and transmitter	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:46
-	185	(chemical adj etching) and (receiver and transmitter)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:46

-	2	5629244.URPN.	USPAT	2002/05/17 17:06
-	22	5639423.URPN.	USPAT	2002/05/17 17:10
-	30	("4219335"   "4596697"   "4598049"   "4632808"   "4673657"   "4676274"   "4683195"   "4708931"   "4737464"   "4759828"   "4908112"   "4920056"   "4952266"   "4960486"   "4963498"   "5000817"   "5003822"   "5006749"   "5129262"   "5212988"   "5220189"   "5229297"   "5252294"   "5270183"   "5296375"   "5304487"   "5385709"   "5427946"   "5486335"   "5498392").PN.	USPAT	2002/05/17 17:12
-	5	5282921.URPN.	USPAT	2002/05/17 17:16
-	5	("2912497"   "2967907"   "3806643"   "4423137"   "4509162").PN.	USPAT	2002/05/17 17:17
-	256	(438/381).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 17:24
-	48	rf adj etch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 17:41
-	5	5817573.URPN.	USPAT	2002/05/17 17:38
-	5	5817573.URPN.	USPAT	2002/05/17 17:38
-	14	("5141897"   "5167760"   "5231051"   "5233223"   "5254498"   "5312773"   "5326427"   "5358621"   "5364817"   "5374849"   "5387550"   "5397742"   "5407861"   "5496773").PN.	USPAT	2002/05/17 17:38
-	1	"non-contact detection system" and (etch or etching)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 17:43
-	435	high adj frequency adj detection or high adj frequency adj detector	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 17:44
-	330600	etch or etching	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 17:45
-	653629	silicon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 17:45
-	6	(high adj frequency adj detection or high adj frequency adj detector) and (etch or etching) and silicon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 17:45
-	0	chemical adj etching and (high adj frequency adj detection or high adj frequency adj detector)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 17:48
-	1	"secondary ion emission spectroscopy"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 11:03

-	8	"leybold-inficon"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 11:04
-	405	radio adj waves and etching	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 11:05
-	1133640	semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 11:06
-	193	(radio adj waves and etching) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 11:42
-	0	(156/627.1).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 11:42
-	0	(156/627).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 11:46
-	2	("6210981").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 11:55
-	5	("5140164"   "5629244"   "5733820"   "5821549"   "5844416").PN.	USPAT	2002/05/19 11:46
-	18	("4639301"   "4818872"   "4843330"   "4851097"   "4875971"   "4912327"   "4924287"   "4943769"   "4954773"   "4996659"   "5057773"   "5089774"   "5140164"   "5155368"   "5376883"   "5430305"   "5521517"   "5525806").PN.	USPAT	2002/05/19 11:47
-	5	5844416.URPN.	USPAT	2002/05/19 11:49
-	3	6210981.URPN.	USPAT	2002/05/19 11:50
-	9	("5127984"   "RE34425"   "5268065"   "5413941"   "5433650"   "5433651"   "5856871"   "5891352"   "6210981").PN.	USPAT	2002/05/19 11:52
-	0	6368881.URPN.	USPAT	2002/05/19 11:54
-	3	("5516339").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 11:56
-	2	5516339.URPN.	USPAT	2002/05/19 11:55
-	31	("4303748"   "4547440"   "4556614"   "4589197"   "4594299"   "4631810"   "4638407"   "4654279"   "4683181"   "4722877"   "4748542"   "4758483"   "4792504"   "4818643"   "4822701"   "4830939"   "4902589"   "4908283"   "4911995"   "4925751"   "4935317"   "4997732"   "5009970"   "5011501"   "5013619"   "5037712"   "5041346"   "5089027"   "5102752"   "5176968"   "5409786").PN.	USPAT	2002/05/19 11:55

-	1	"thickness detection" same radio	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 11:58
-	4	"thickness detection" same rf	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 11:58
-	14	"insitu" and etching and (rf or radio) and (monitoring or detection)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:03
-	6	("4115184"   "4207137"   "4354154"   "4963819"   "5175472"   "5273610").PN.	USPAT	2002/05/19 12:08
-	29	5467013.URPN.	USPAT	2002/05/19 12:09
-	144	"lateral undercut" or "lateral under-cut"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:33
-	5	(( "6063642" ) or ( "5559058" ) ).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:45
-	0	("physical adj measured and undercut").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:45
-	0	("physical adj measured same undercut").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:46
-	0	("physical adj measured same "undercut").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:46
-	0	("undercut").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:46
-	43622	undercut	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 13:33
-	1134671	measured	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:47
-	4169	undercut and measured	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:47
-	653629	silicon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:47

-	1209	(undercut and measured ) and silicon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:47
-	596606	lateral	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:48
-	422	((undercut and measured ) and silicon ) and lateral	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:48
-	1969	insitu	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:48
-	1	((undercut and measured ) and silicon ) and lateral) and insitu	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 13:32
-	3	("4763183"   "5114233"   "5539766").PN.	USPAT	2002/05/19 13:03
-	5	5739909.URPN.	USPAT	2002/05/19 13:04
-	252	(324/329).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 13:32
-	57	(324/341).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 13:32
-	264	(324/338).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 13:32
-	9	(324/364).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 13:33
-	301	(324/71.5).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 13:33
-	609	undercut and ((324/329).CCLS.) or ((324/341).CCLS.) or ((324/338).CCLS.) or ((324/364).CCLS.) or ((324/71.5).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 13:34
-	88	silicon and (undercut and ((324/329).CCLS.) or ((324/341).CCLS.) or ((324/338).CCLS.) or ((324/364).CCLS.) or ((324/71.5).CCLS.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 13:34
-	2	5027064.URPN.	USPAT	2002/05/19 13:42
-	1926	sra or "surface resistance analyzer"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 15:22

-	43622	undercut	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 15:22
-	1133640	semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 15:23
-	0	(sra or "surface resistance analyzer") and undercut and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 15:23
-	276	(sra or "surface resistance analyzer") and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 15:23
-	128630	etch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 15:23
-	4	((sra or "surface resistance analyzer") and semiconductor) and etch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 15:23
-	256	(438/381).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 17:08
-	70905	inductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 17:09
-	76	((438/381).CCLS.) and inductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/21 09:31
-	17	((438/381).CCLS.) and inductor and polysilicon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/21 09:32
-	961	(257/48).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:01
-	817207	coil	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:01
-	15	((257/48).CCLS.) and coil	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:03
-	1481	lateral adj etch or lateral adj etching	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:03

-	128	coil and (lateral adj etch or lateral adj etching)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:07
-	2082394	measure or measured or measuring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:08
-	81	(coil and (lateral adj etch or lateral adj etching)) and (measure or measured or measuring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:08
-	2	("5739909").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:24
-	11	5739909.URPN.	USPAT	2003/06/02 08:22
-	3	("4763183"   "5114233"   "5539766").PN.	USPAT	2003/06/02 08:23
-	182	scatterometry	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:24
-	18	coil and scatterometry	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:37
-	844792	monitor or monitoring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:38
-	23	coil and (lateral adj etch or lateral adj etching) and (monitor or monitoring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:44
-	0	6340603.URPN.	USPAT	2003/06/02 08:41
-	10	("4522681"   "4817815"   "5007982"   "5242536"   "5877032"   "5910011"   "5926740"   "6040248"   "6121123"   "6141183").PN.	USPAT	2003/06/02 08:41
-	0	6340603.URPN.	USPAT	2003/06/02 08:43
-	77609	inductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:45
-	5	(lateral adj etch or lateral adj etching) and (monitor or monitoring) and inductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:46
-	1096	(438/14).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:46
-	1	(lateral adj etch or lateral adj etching) and ((438/14).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:47